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NORME INTERNATIONALE

Semiconductor devices – Mechanical and climatic test methods – Part 21: Solderability

Dispositifs à semiconducteur – Méthodes d'essai mécaniques et climatiques – Partie 21: Brasabilité

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 21: Solderability

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International Standard IEC 60749-21 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard cancels and replaces the first edition published in 2004 and constitutes a technical revision. The significant change is the inclusion of Pb (lead)–free backward compatibility.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2082/FDIS	47/2089/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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